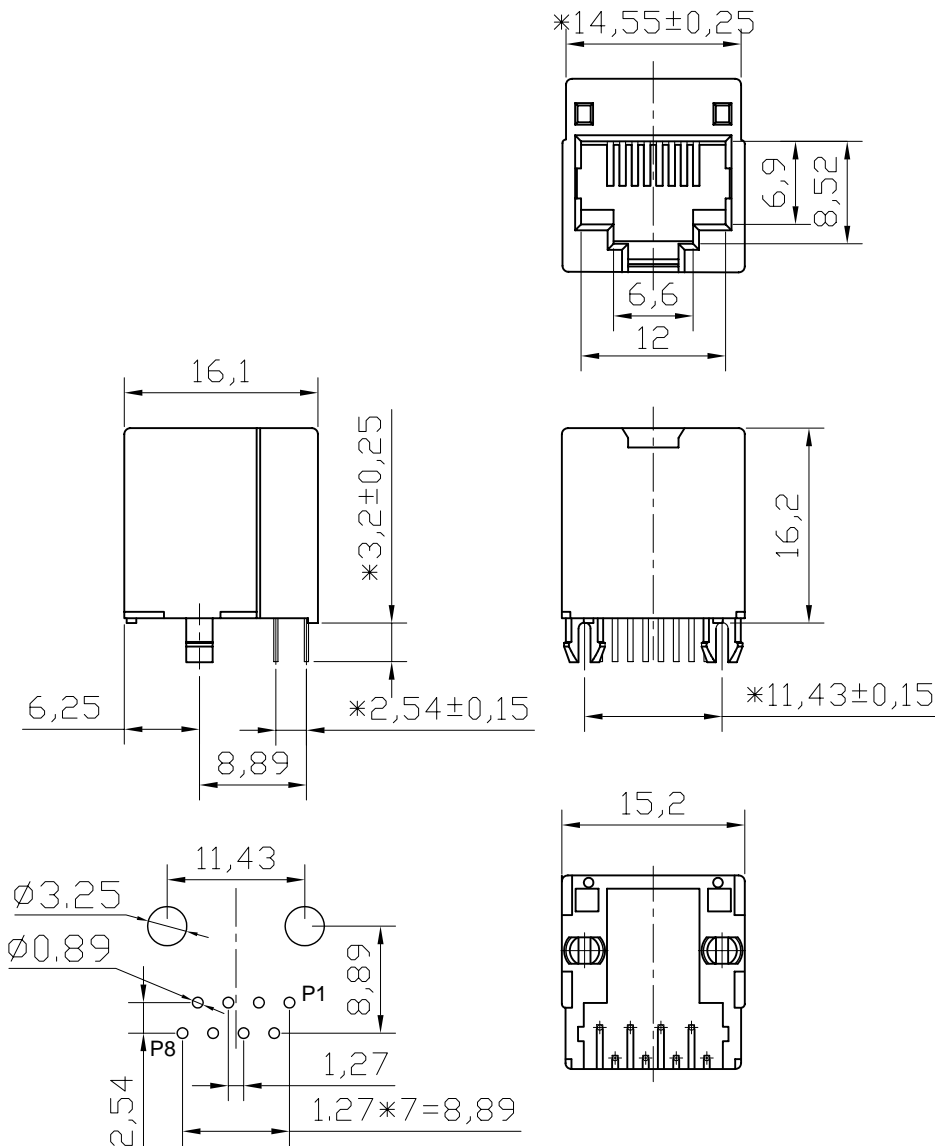


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD



PC Board Layout
Component Side Shown

NOTES:

MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL :PHOSPHOR BRONZE $\phi=0.46\text{mm}$.
3. PLATING :SELECTING GOLD PLATING $3\mu\sim 50\mu$ OVER NICKEL

ELECTRICAL:

1. VOLTAGE RATING :125 VAC RMS.
2. CURRENT RATING :1.5 AMP.
3. CONTACT RESISTANCE :30 MILLIOHMS MAX.
4. INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

1. DURRABILITY: :750 CYCLES MIN.
2. PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

1. STORAGE : -40° C TO 85° C.
2. OPERATION : 0° C TO 70° C.

DETACHED LISTS	MM (INCH)		DFTO:	DATE: 2007.05	<h2 style="text-align: center;">Coorle 库乐科技</h2>
	TOLERANCES EXCEPT AS NOTED		CHKD:	DATE: 2007.05.05	
			MFO:	DATE:	
			APPVL:	DATE:	
MM		MATERIAL :		TITLE	
.0 ± 0.15 ±				RJ45 JACK 5224 8P8C	
.00 ± 0.075 ±				DRAWING NO. TE521001	
.000 ± 0.05 ±				/PART NO.	
ANGLES ± 0.5		QTY :		SIZE REV	
THIRD ANGLE PROJECTION		FINISH :		A3 0	
		SCALE :		DD NOT SCALE DRAWING	
				SHEET X OF Y	

8

7

6

5

4

3

2

1

H
G
F
E
D
C
B
A